

WHAT IS CLAIMED IS:

- 1 1. A method for processing a plurality of microelectromechanical-systems (MEMS) dice, the method comprising:
 - 3 securing the plurality of MEMS dice in a holder; and
 - 4 performing a process step on the plurality of MEMS dice while secured in the holder.
- 1 2. The method recited in claim 1 wherein the process step is performed simultaneously on the MEMS dice while secured in the holder.
- 1 3. The method recited in claim 1 wherein the plurality of MEMS dice include unreleased MEMS dice.
- 1 4. The method recited in claim 1 wherein performing the process step comprises immersing the holder with the plurality of secured MEMS dice in a liquid.
- 1 5. The method recited in claim 4 wherein the liquid comprises a solution of hydrofluoric acid.
- 1 6. The method recited in claim 4 wherein the liquid comprises deionized water.
- 1 7. The method recited in claim 4 wherein performing the process step further comprises immersing the holder with the plurality of secured MEMS dice in a second liquid.
- 1 8. The method recited in claim 4 wherein performing the process step further comprises performing critical point drying on the plurality of MEMS dice.
- 1 9. The method recited in claim 1 wherein performing the process step comprises testing the plurality of MEMS dice.
- 1 10. The method recited in claim 1 wherein performing the process step comprises performing a step in packaging the plurality of MEMS dice

- 1 12. The method recited in claim 1 wherein the holder is made of a
2 fluoropolymer resin.
- 1 13. The method recited in claim 12 wherein the holder is made of teflon^{*}.
- 1 14. The method recited in claim 1 further comprising preparing the
2 plurality of MEMS dice by dicing a processed wafer.
- 1 15. An article comprising:
2 a structural body having a plurality of stations, each such station being adapted
3 to secure a microelectromechanical-systems (MEMS) die.
- 1 16. The article recited in claim 15 wherein each such station comprises:
2 a recess within the structural body shaped to secure an edge of the MEMS die;
3 and
4 a flexible retaining arm adapted to retain the MEMS die within the recess.
- 1 17. The article recited in claim 16 wherein the flexible retaining arm
2 includes a notch shaped for engagement with a tool for flexing the flexible retaining arm.
- 1 18. The article recited in claim 15 wherein each such station includes an
2 access to an underside of the MEMS die.
- 1 19. The article recited in claim 18 wherein the access comprises a hole in
2 the structural body.
- 1 20. The article recited in claim 18 wherein the access comprises a slot in
2 the structural body.
- 1 21. The article recited in claim 15 wherein the structural body is circularly
2 symmetric and the plurality of stations are configured symmetrically about a central axis of
3 the structural body.
- 1 22. The article recited in claim 15 wherein the article is formed as a single
2 fluoropolymer resin.

1 24. The article recited in claim 23 wherein the article is formed of teflon*.

1 25. An article comprising:

2 a structural body having a plurality of means for securing a

3 microelectromechanical-systems (MEMS) die.

1 26. The article recited in claim 25 wherein each such means for securing

2 includes flexible means for retaining the MEMS die within a recess in the structural body.

1 27. The article recited in claim 25 wherein the structural body is circularly

2 symmetric and the plurality of means for securing are configured symmetrically about a

3 central axis of the structural body.